Preface

Following the great progress made in applied materials and electronics engineering, the 2013 2nd International Conference on Applied Materials and Electronics Engineering (AMEE 2013) aimed at providing a forum for presentation and discussion of state-of-the-art development in Nanoscience and Nanotechnology, Structural and Materials Science, Building Materials, Chemical and Materials Engineering, Environmental Engineering and Materials Science, Electrical and Electrical Materials, Mechatronics, MEMS/NEMS, Information and Computational Materials Science, Material Science and Technology, Construction technology and Materials Science and other related fields. Emphasis was given to basic methodologies, scientific development and engineering applications.

This conference is co-sponsored by International Association for Scientific and High Technology and International Science and Engineering Research Center, and it is technical co-sponsored by Academy Publisher. The purpose of AMEE 2013 is to bring together researchers and practitioners from academia, industry, and government to exchange their research ideas and results in the areas of the conference. In addition, the participants of the conference will have a chance to hear from renowned keynote speakers Prof. S. C. Tjong from City University of Hong Kong.

We would like to thank all the participants and the authors for their contributions. We would also like to gratefully acknowledge the production supervisor Mr. Thomas Wohlbier, who enthusiastically supports the conference. In particular, we appreciate the full heart support of all the reviewers and staff members of the conference. We hope that AMEE 2013 will be successful and enjoyable to all participants and look forward to seeing all of you next year at the AMEE 2014.

January, 2013

Brendan Gan
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